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### Applications of "[Embedded - Microcontrollers](#)"

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I <sup>2</sup> C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-QFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=s9s08aw60e5mfue">https://www.e-xfl.com/pro/item?MUrl=&amp;PartUrl=s9s08aw60e5mfue</a>

Part Number	Package Description	Original (gold wire) package document number	Current (copper wire) package document number
MC68HC908JW32	48 QFN	98ARH99048A	98ASA00466D
MC9S08AC16			
MC9S908AC60			
MC9S08AC128			
MC9S08AW60			
MC9S08GB60A			
MC9S08GT16A			
MC9S08JM16			
MC9S08JM60			
MC9S08LL16			
MC9S08QE128			
MC9S08QE32			
MC9S08RG60			
MCF51CN128			
MC9RS08LA8	48 QFN	98ARL10606D	98ASA00466D
MC9S08GT16A	32 QFN	98ARH99035A	98ASA00473D
MC9S908QE32	32 QFN	98ARE10566D	98ASA00473D
MC9S908QE8	32 QFN	98ASA00071D	98ASA00736D
MC9S08JS16	24 QFN	98ARL10608D	98ASA00734D
MC9S08QB8			
MC9S08QG8	24 QFN	98ARL10605D	98ASA00474D
MC9S08SH8	24 QFN	98ARE10714D	98ASA00474D
MC9RS08KB12	24 QFN	98ASA00087D	98ASA00602D
MC9S08QG8	16 QFN	98ARE10614D	98ASA00671D
MC9RS08KB12	8 DFN	98ARL10557D	98ASA00672D
MC9S08QG8			
MC9RS08KA2	6 DFN	98ARL10602D	98ASA00735D

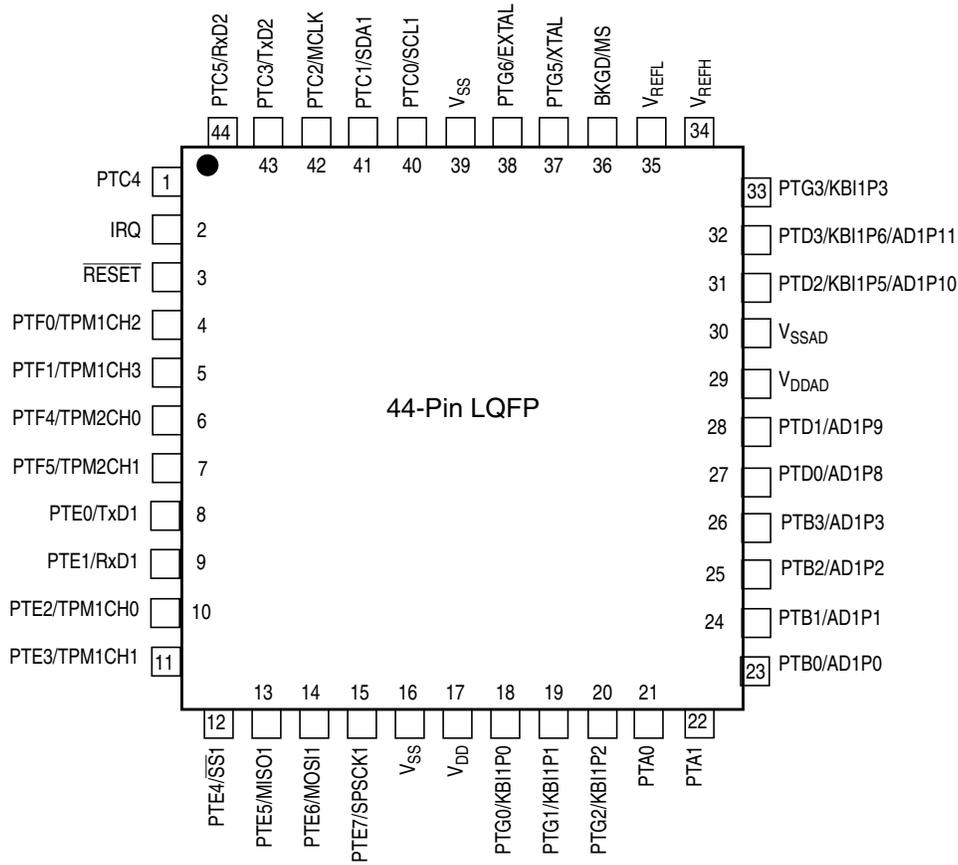


Figure 2-3. MC9S08AW60 Series in 44-Pin LQFP Package

## 2.3 Recommended System Connections

Figure 2-4 shows pin connections that are common to almost all MC9S08AW60 Series application systems.

After waking up from stop2, the PPDF bit in SPMSC2 is set. This flag may be used to direct user code to go to a stop2 recovery routine. PPDF remains set and the I/O pin states remain latched until a logic 1 is written to PPDACK in SPMSC2.

To maintain I/O state for pins that were configured as general-purpose I/O, the user must restore the contents of the I/O port registers, which have been saved in RAM, to the port registers before writing to the PPDACK bit. If the port registers are not restored from RAM before writing to PPDACK, then the register bits will assume their reset states when the I/O pin latches are opened and the I/O pins will switch to their reset states.

For pins that were configured as peripheral I/O, the user must reconfigure the peripheral module that interfaces to the pin before writing to the PPDACK bit. If the peripheral module is not enabled before writing to PPDACK, the pins will be controlled by their associated port control registers when the I/O latches are opened.

### 3.6.2 Stop3 Mode

Stop3 mode is entered by executing a STOP instruction under the conditions as shown in Table 3-1. The states of all of the internal registers and logic, RAM contents, and I/O pin states are maintained.

Stop3 can be exited by asserting  $\overline{\text{RESET}}$ , or by an interrupt from one of the following sources: the real-time interrupt (RTI), LVD, ADC, IRQ, or the KBI.

If stop3 is exited by means of the  $\overline{\text{RESET}}$  pin, then the MCU is reset and operation will resume after taking the reset vector. Exit by means of one of the internal interrupt sources results in the MCU taking the appropriate interrupt vector.

### 3.6.3 Active BDM Enabled in Stop Mode

Entry into the active background mode from run mode is enabled if the ENBDM bit in BDCSCR is set. This register is described in Chapter 15, “Development Support” of this data sheet. If ENBDM is set when the CPU executes a STOP instruction, the system clocks to the background debug logic remain active when the MCU enters stop mode so background debug communication is still possible. In addition, the voltage regulator does not enter its low-power standby state but maintains full internal regulation. If the user attempts to enter stop2 with ENBDM set, the MCU will instead enter stop3.

Most background commands are not available in stop mode. The memory-access-with-status commands do not allow memory access, but they report an error indicating that the MCU is in either stop or wait mode. The BACKGROUND command can be used to wake the MCU from stop and enter active background mode if the ENBDM bit is set. After entering background debug mode, all background commands are available. Table 3-2 summarizes the behavior of the MCU in stop when entry into the background debug mode is enabled.

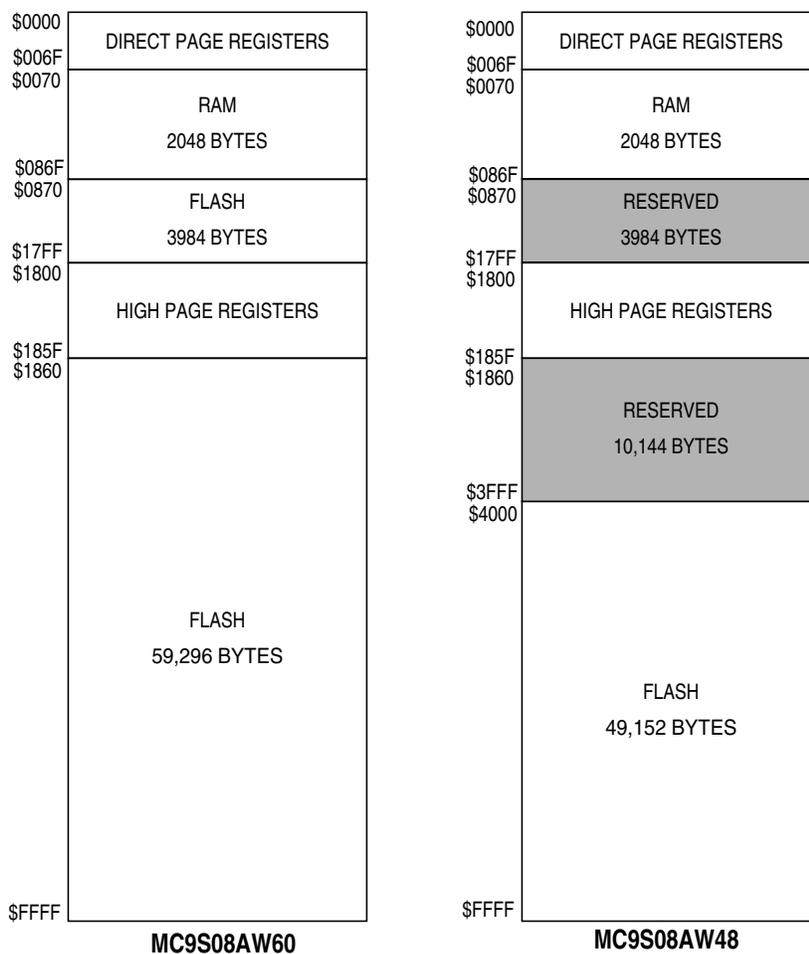


Figure 4-1. MC9S08AW60 and MC9S08AW48 Memory Map

**Table 4-2. Direct-Page Register Summary (Sheet 1 of 3)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
\$0000	PTAD	PTAD7	PTAD6	PTAD5	PTAD4	PTAD3	PTAD2	PTAD1	PTAD0
\$0001	PTADD	PTADD7	PTADD6	PTADD5	PTADD4	PTADD3	PTADD2	PTADD1	PTADD0
\$0002	PTBD	PTBD7	PTBD6	PTBD5	PTBD4	PTBD3	PTBD2	PTBD1	PTBD0
\$0003	PTBDD	PTBDD7	PTBDD6	PTBDD5	PTBDD4	PTBDD3	PTBDD2	PTBDD1	PTBDD0
\$0004	PTCD	0	PTCD6	PTCD5	PTCD4	PTCD3	PTCD2	PTCD1	PTCD0
\$0005	PTCDD	0	PTCDD6	PTCDD5	PTCDD4	PTCDD3	PTCDD2	PTCDD1	PTCDD0
\$0006	PTDD	PTDD7	PTDD6	PTDD5	PTDD4	PTDD3	PTDD2	PTDD1	PTDD0
\$0007	PTDDD	PTDDD7	PTDDD6	PTDDD5	PTDDD4	PTDDD3	PTDDD2	PTDDD1	PTDDD0
\$0008	PTED	PTED7	PTED6	PTED5	PTED4	PTED3	PTED2	PTED1	PTED0
\$0009	PTEDD	PTEDD7	PTEDD6	PTEDD5	PTEDD4	PTEDD3	PTEDD2	PTEDD1	PTEDD0
\$000A	PTFD	PTFD7	PTFD6	PTFD5	PTFD4	PTFD3	PTFD2	PTFD1	PTFD0
\$000B	PTFDD	PTFDD7	PTFDD6	PTFDD5	PTFDD4	PTFDD3	PTFDD2	PTFDD1	PTFDD0
\$000C	PTGD	0	PTGD6	PTGD5	PTGD4	PTGD3	PTGD2	PTGD1	PTGD0
\$000D	PTGDD	0	PTGDD6	PTGDD5	PTGDD4	PTGDD3	PTGDD2	PTGDD1	PTGDD0
\$000E– \$000F	Reserved	—	—	—	—	—	—	—	—
\$0010	ADC1SC1	COCO	AIEN	ADCO	ADCH				
\$0011	ADC1SC2	ADACT	ADTRG	ACFE	ACFGT	0	0	R	R
\$0012	ADC1RH	0	0	0	0	0	0	ADR9	ADR8
\$0013	ADC1RL	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	ADR0
\$0014	ADC1CVH	0	0	0	0	0	0	ADCV9	ADCV8
\$0015	ADC1CVL	ADCV7	ADCV6	ADCV5	ADCV4	ADCV3	ADCV2	ADCV1	ADCV0
\$0016	ADC1CFG	ADLPC	ADIV		ADLSMP	MODE		ADICLK	
\$0017	APCTL1	ADPC7	ADPC6	ADPC5	ADPC4	ADPC3	ADPC2	ADPC1	ADPC0
\$0018	APCTL2	ADPC15	ADPC14	ADPC13	ADPC12	ADPC11	ADPC10	ADPC9	ADPC8
\$0019	APCTL3	ADPC23	ADPC22	ADPC21	ADPC20	ADPC19	ADPC18	ADPC17	ADPC16
\$001A– \$001B	Reserved	—	—	—	—	—	—	—	—
\$001C	IRQSC	0	0	IRQEDG	IRQPE	IRQF	IRQACK	IRQIE	IRQMOD
\$001D	Reserved	—	—	—	—	—	—	—	—
\$001E	KBI1SC	KBEDG7	KBEDG6	KBEDG5	KBEDG4	KBF	KBACK	KBIE	KBIMOD
\$001F	KBI1PE	KBIPE7	KBIPE6	KBIPE5	KBIPE4	KBIPE3	KBIPE2	KBIPE1	KBIPE0
\$0020	TPM1SC	TOF	TOIE	CPWMS	CLKSB	CLKSA	PS2	PS1	PS0
\$0021	TPM1CNTH	Bit 15	14	13	12	11	10	9	Bit 8
\$0022	TPM1CNTL	Bit 7	6	5	4	3	2	1	Bit 0
\$0023	TPM1MODH	Bit 15	14	13	12	11	10	9	Bit 8
\$0024	TPM1MODL	Bit 7	6	5	4	3	2	1	Bit 0
\$0025	TPM1C0SC	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	0	0
\$0026	TPM1C0VH	Bit 15	14	13	12	11	10	9	Bit 8
\$0027	TPM1C0VL	Bit 7	6	5	4	3	2	1	Bit 0

**Table 4-3. High-Page Register Summary (Sheet 2 of 2)**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
\$1846	<b>PTBDS</b>	PTBDS7	PTBDS6	PTBDS5	PTBDS4	PTBDS3	PTBDS2	PTBDS1	PTBDS0
\$1847	Reserved	—	—	—	—	—	—	—	—
\$1848	<b>PTCPE</b>	0	PTCPE6	PTCPE5	PTCPE4	PTCPE3	PTCPE2	PTCPE1	PTCPE0
\$1849	<b>PTCSE</b>	0	PTCSE6	PTCSE5	PTCSE4	PTCSE3	PTCSE2	PTCSE1	PTCSE0
\$184A	<b>PTCDS</b>	0	PTCDS6	PTCDS5	PTCDS4	PTCDS3	PTCDS2	PTCDS1	PTCDS0
\$184B	Reserved	—	—	—	—	—	—	—	—
\$184C	<b>PTDPE</b>	PTDPE7	PTDPE6	PTDPE5	PTDPE4	PTDPE3	PTDPE2	PTDPE1	PTDPE0
\$184D	<b>PTDSE</b>	PTDSE7	PTDSE6	PTDSE5	PTDSE4	PTDSE3	PTDSE2	PTDSE1	PTDSE0
\$184E	<b>PTDDS</b>	PTDDS7	PTDDS6	PTDDS5	PTDDS4	PTDDS3	PTDDS2	PTDDS1	PTDDS0
\$184F	Reserved	—	—	—	—	—	—	—	—
\$1850	<b>PTEPE</b>	PTEPE7	PTEPE6	PTEPE5	PTEPE4	PTEPE3	PTEPE2	PTEPE1	PTEPE0
\$1851	<b>PTESE</b>	PTESE7	PTESE6	PTESE5	PTESE4	PTESE3	PTESE2	PTESE1	PTESE0
\$1852	<b>PTEDS</b>	PTEDS7	PTEDS6	PTEDS5	PTEDS4	PTEDS3	PTEDS2	PTEDS1	PTEDS0
\$1853	Reserved	—	—	—	—	—	—	—	—
\$1854	<b>PTFPE</b>	PTFPE7	PTFPE6	PTFPE5	PTFPE4	PTFPE3	PTFPE2	PTFPE1	PTFPE0
\$1855	<b>PTFSE</b>	PTFSE7	PTFSE6	PTFSE5	PTFSE4	PTFSE3	PTFSE2	PTFSE1	PTFSE0
\$1856	<b>PTFDS</b>	PTFDS7	PTFDS6	PTFDS5	PTFDS4	PTFDS3	PTFDS2	PTFDS1	PTFDS0
\$1857	Reserved	—	—	—	—	—	—	—	—
\$1858	<b>PTGPE</b>	0	PTGPE6	PTGPE5	PTGPE4	PTGPE3	PTGPE2	PTGPE1	PTGPE0
\$1859	<b>PTGSE</b>	0	PTGSE6	PTGSE5	PTGSE4	PTGSE3	PTGSE2	PTGSE1	PTGSE0
\$185A	<b>PTGDS</b>	0	PTGDS6	PTGDS5	PTGDS4	PTGDS3	PTGDS2	PTGDS1	PTGDS0
\$185B– \$185F	Reserved	—	—	—	—	—	—	—	—

<sup>1</sup> This reserved bit must always be written to 0.

Nonvolatile FLASH registers, shown in Table 4-4, are located in the FLASH memory. These registers include an 8-byte backdoor key which optionally can be used to gain access to secure memory resources. During reset events, the contents of NVPROT and NVOPT in the nonvolatile register area of the FLASH memory are transferred into corresponding FPROT and FOPT working registers in the high-page registers to control security and block protection options.

**Table 4-4. Nonvolatile Register Summary**

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
\$FFB0 – \$FFB7	NVBACKKEY	8-Byte Comparison Key							
\$FFB8 – \$FFBB	Reserved	—	—	—	—	—	—	—	—
\$FFBC	Reserved for stor- age of 250 kHz ICGTRM value	—	—	—	—	—	—	—	—
\$FFBD	NVPROT	FPS7	FPS6	FPS5	FPS4	FPS3	FPS2	FPS1	FPDIS
\$FFBE	Reserved for stor- age of 243 kHz ICGTRM value	—	—	—	—	—	—	—	—
\$FFBF	NVOPT	KEYEN	FNORED	0	0	0	0	SEC01	SEC00

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the FLASH if needed (normally through the background debug interface) and verifying that FLASH is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC01:SEC00) to the unsecured state (1:0).

## 4.3 RAM

The MC9S08AW60 Series includes static RAM. The locations in RAM below \$0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait, stop2, or stop3 mode. At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention.

For compatibility with older M68HC05 MCUs, the HCS08 resets the stack pointer to \$00FF. In the MC9S08AW60 Series, it is usually best to re-initialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM in the Freescale-provided equate file).

---

```
LDHX    #RamLast+1    ;point one past RAM
TXS                    ;SP<-(H:X-1)
```

---

## Chapter 7

# Central Processor Unit (S08CPUV2)

### 7.1 Introduction

This section provides summary information about the registers, addressing modes, and instruction set of the CPU of the HCS08 family. For a more detailed discussion, refer to the *HCS08 Family Reference Manual, volume 1*, Freescale Semiconductor document order number HCS08RMV1/D.

The HCS08 CPU is fully source- and object-code-compatible with the M68HC08 CPU. Several instructions and enhanced addressing modes were added to improve C compiler efficiency and to support a new background debug system which replaces the monitor mode of earlier M68HC08 microcontrollers (MCU).

#### 7.1.1 Features

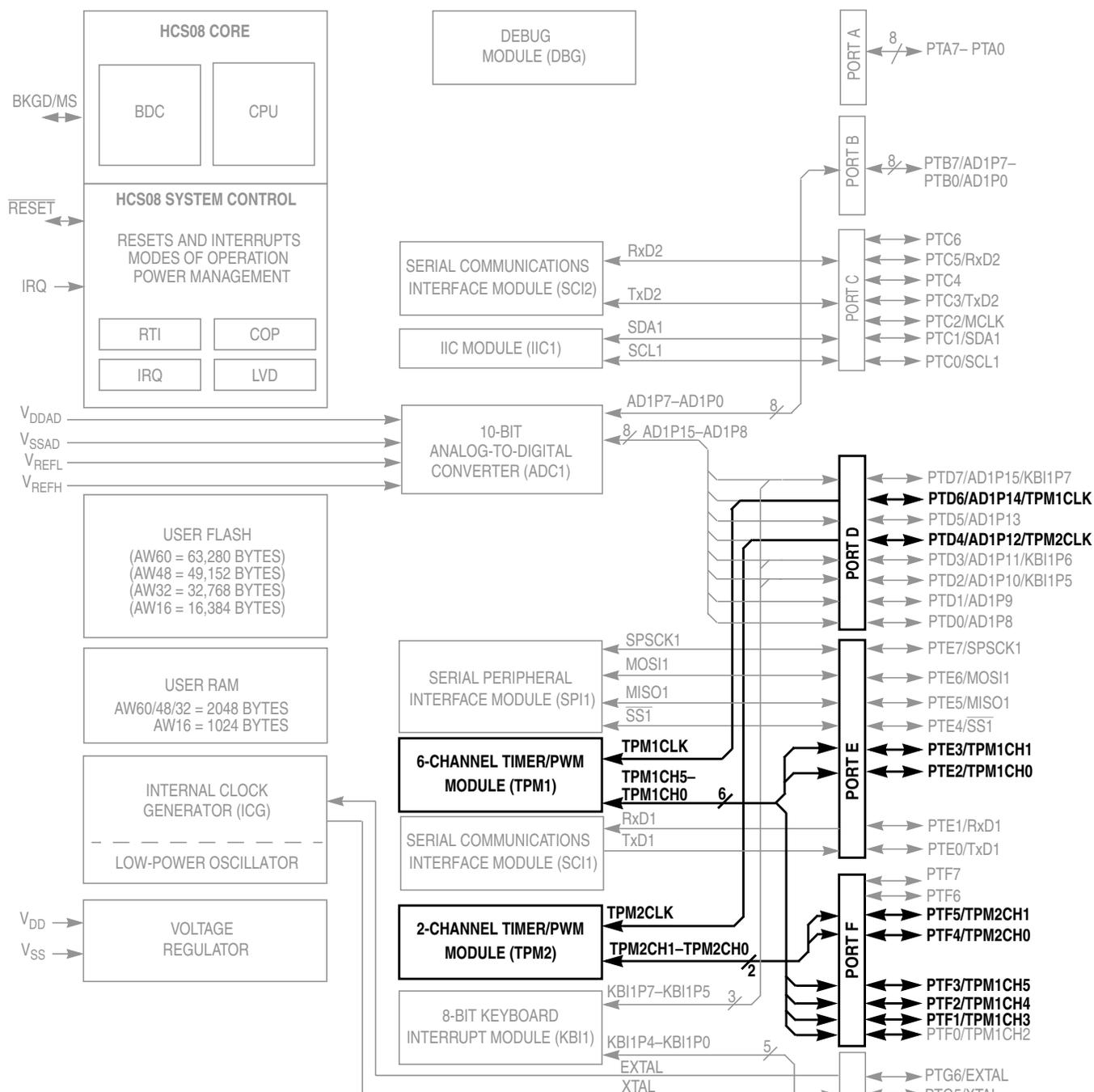
Features of the HCS08 CPU include:

- Object code fully upward-compatible with M68HC05 and M68HC08 Families
- All registers and memory are mapped to a single 64-Kbyte address space
- 16-bit stack pointer (any size stack anywhere in 64-Kbyte address space)
- 16-bit index register (H:X) with powerful indexed addressing modes
- 8-bit accumulator (A)
- Many instructions treat X as a second general-purpose 8-bit register
- Seven addressing modes:
  - Inherent — Operands in internal registers
  - Relative — 8-bit signed offset to branch destination
  - Immediate — Operand in next object code byte(s)
  - Direct — Operand in memory at 0x0000–0x00FF
  - Extended — Operand anywhere in 64-Kbyte address space
  - Indexed relative to H:X — Five submodes including auto increment
  - Indexed relative to SP — Improves C efficiency dramatically
- Memory-to-memory data move instructions with four address mode combinations
- Overflow, half-carry, negative, zero, and carry condition codes support conditional branching on the results of signed, unsigned, and binary-coded decimal (BCD) operations
- Efficient bit manipulation instructions
- Fast 8-bit by 8-bit multiply and 16-bit by 8-bit divide instructions
- STOP and WAIT instructions to invoke low-power operating modes

- IX = 16-bit indexed no offset
- IX+ = 16-bit indexed no offset, post increment (CBEQ and MOV only)
- IX1 = 16-bit indexed with 8-bit offset from H:X
- IX1+ = 16-bit indexed with 8-bit offset, post increment (CBEQ only)
- IX2 = 16-bit indexed with 16-bit offset from H:X
- REL = 8-bit relative offset
- SP1 = Stack pointer with 8-bit offset
- SP2 = Stack pointer with 16-bit offset

Table 7-2. HCS08 Instruction Set Summary (Sheet 1 of 7)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Bus Cycles <sup>1</sup>
			V	H	I	N	Z	C				
ADC #opr8i ADC opr8a ADC opr16a ADC oprx16,X ADC oprx8,X ADC ,X ADC oprx16,SP ADC oprx8,SP	Add with Carry	$A \leftarrow (A) + (M) + (C)$	↑	↑	–	↑	↑	↑	IMM DIR EXT IX2 IX1 IX SP2 SP1	A9 B9 C9 D9 E9 F9 9ED9 9EE9	ii dd hh ll ee ff ee ff ee ff ee ff ff	2 3 4 4 3 3 5 4
ADD #opr8i ADD opr8a ADD opr16a ADD oprx16,X ADD oprx8,X ADD ,X ADD oprx16,SP ADD oprx8,SP	Add without Carry	$A \leftarrow (A) + (M)$	↑	↑	–	↑	↑	↑	IMM DIR EXT IX2 IX1 IX SP2 SP1	AB BB CB DB EB FB 9EDB 9EEB	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
AIS #opr8i	Add Immediate Value (Signed) to Stack Pointer	$SP \leftarrow (SP) + (M)$ M is sign extended to a 16-bit value	–	–	–	–	–	–	IMM	A7	ii	2
AIX #opr8i	Add Immediate Value (Signed) to Index Register (H:X)	$H:X \leftarrow (H:X) + (M)$ M is sign extended to a 16-bit value	–	–	–	–	–	–	IMM	AF	ii	2
AND #opr8i AND opr8a AND opr16a AND oprx16,X AND oprx8,X AND ,X AND oprx16,SP AND oprx8,SP	Logical AND	$A \leftarrow (A) \& (M)$	0	–	–	↑	↑	–	IMM DIR EXT IX2 IX1 IX SP2 SP1	A4 B4 C4 D4 E4 F4 9ED4 9EE4	ii dd hh ll ee ff ff ff ee ff ff	2 3 4 4 3 3 5 4
ASL opr8a ASLA ASLX ASL oprx8,X ASL ,X ASL oprx8,SP	Arithmetic Shift Left (Same as LSL)		↑	–	–	↑	↑	↑	DIR INH INH IX1 IX SP1	38 48 58 68 78 9E68	dd ff ff ff	5 1 1 5 4 6
ASR opr8a ASRA ASRX ASR oprx8,X ASR ,X ASR oprx8,SP	Arithmetic Shift Right		↑	–	–	↑	↑	↑	DIR INH INH IX1 IX SP1	37 47 57 67 77 9E67	dd ff ff ff ff	5 1 1 5 4 6
BCC rel	Branch if Carry Bit Clear	Branch if (C) = 0	–	–	–	–	–	–	REL	24	rr	3



**NOTES:**

1. Port pins are software configurable with pullup device if input port.
2. Pin contains software configurable pullup/pulldown device if IRQ is enabled (IRQPE = 1). Pulldown is enabled if rising edge detect is selected (IRQEDG = 1)
3. IRQ does not have a clamp diode to V<sub>DD</sub>. IRQ should not be driven above V<sub>DD</sub>.
4. Pin contains integrated pullup device.
5. Pins PTD7, PTD3, PTD2, and PTG4 contain both pullup and pulldown devices. Pulldown enabled when KBI is enabled (KBIPE<sub>n</sub> = 1) and rising edge is selected (KBEDG<sub>n</sub> = 1).

**Figure 10-1. Block Diagram Highlighting the TPM Module**

### 10.5.3 Center-Aligned PWM Mode

This type of PWM output uses the up-/down-counting mode of the timer counter ( $CPWMS = 1$ ). The output compare value in  $TPMxCnVH:TPMxCnVL$  determines the pulse width (duty cycle) of the PWM signal and the period is determined by the value in  $TPMxMODH:TPMxMODL$ .

$TPMxMODH:TPMxMODL$  should be kept in the range of  $0x0001$  to  $0x7FFF$  because values outside this range can produce ambiguous results.  $ELSnA$  will determine the polarity of the CPWM output.

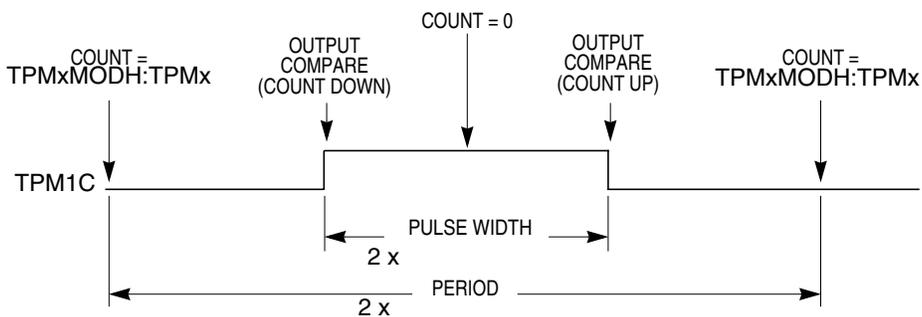
$$\text{pulse width} = 2 \times (\text{TPMxCnVH:TPMxCnVL}) \quad \text{Eqn. 10-1}$$

$$\begin{aligned} \text{period} &= 2 \times (\text{TPMxMODH:TPMxMODL}); \\ \text{for } \text{TPMxMODH:TPMxMODL} &= 0x0001\text{--}0x7FFF \end{aligned} \quad \text{Eqn. 10-2}$$

If the channel value register  $TPMxCnVH:TPMxCnVL$  is zero or negative (bit 15 set), the duty cycle will be 0%. If  $TPMxCnVH:TPMxCnVL$  is a positive value (bit 15 clear) and is greater than the (nonzero) modulus setting, the duty cycle will be 100% because the duty cycle compare will never occur. This implies the usable range of periods set by the modulus register is  $0x0001$  through  $0x7FFE$  ( $0x7FFF$  if generation of 100% duty cycle is not necessary). This is not a significant limitation because the resulting period is much longer than required for normal applications.

$TPMxMODH:TPMxMODL = 0x0000$  is a special case that should not be used with center-aligned PWM mode. When  $CPWMS = 0$ , this case corresponds to the counter running free from  $0x0000$  through  $0xFFFF$ , but when  $CPWMS = 1$  the counter needs a valid match to the modulus register somewhere other than at  $0x0000$  in order to change directions from up-counting to down-counting.

Figure 10-12 shows the output compare value in the TPM channel registers (multiplied by 2), which determines the pulse width (duty cycle) of the CPWM signal. If  $ELSnA = 0$ , the compare match while counting up forces the CPWM output signal low and a compare match while counting down forces the output high. The counter counts up until it reaches the modulo setting in  $TPMxMODH:TPMxMODL$ , then counts down until it reaches zero. This sets the period equal to two times  $TPMxMODH:TPMxMODL$ .



**Figure 10-12. CPWM Period and Pulse Width ( $ELSnA = 0$ )**

Center-aligned PWM outputs typically produce less noise than edge-aligned PWMs because fewer I/O pin transitions are lined up at the same system clock edge. This type of PWM is also required for some types of motor drives.

Because the HCS08 is a family of 8-bit MCUs, the settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers,  $TPMxMODH$ ,  $TPMxMODL$ ,  $TPMxCnVH$ , and  $TPMxCnVL$ , actually write to buffer registers. Values are

## Chapter 12

### Serial Peripheral Interface (S08SPIV3)

The MC9S08AW60 Series has one serial peripheral interface (SPI) module. The four pins associated with SPI functionality are shared with port E pins 4–7. See Appendix A, “Electrical Characteristics and Timing Specifications,” for SPI electrical parametric information.

### 13.3.5 IIC Data I/O Register (IIC1D)

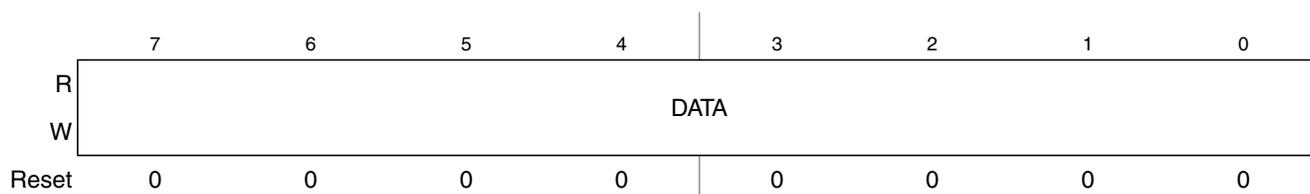


Figure 13-7. IIC Data I/O Register (IIC1D)

Table 13-6. IIC1D Register Field Descriptions

Field	Description
7:0 DATA	<b>Data</b> — In master transmit mode, when data is written to the IIC1D, a data transfer is initiated. The most significant bit is sent first. In master receive mode, reading this register initiates receiving of the next byte of data.

**NOTE**

When transmitting out of master receive mode, the IIC mode should be switched before reading the IIC1D register to prevent an inadvertent initiation of a master receive data transfer.

In slave mode, the same functions are available after an address match has occurred.

Note that the TX bit in IIC1C must correctly reflect the desired direction of transfer in master and slave modes for the transmission to begin. For instance, if the IIC is configured for master transmit but a master receive is desired, then reading the IIC1D will not initiate the receive.

Reading the IIC1D will return the last byte received while the IIC is configured in either master receive or slave receive modes. The IIC1D does not reflect every byte that is transmitted on the IIC bus, nor can software verify that a byte has been written to the IIC1D correctly by reading it back.

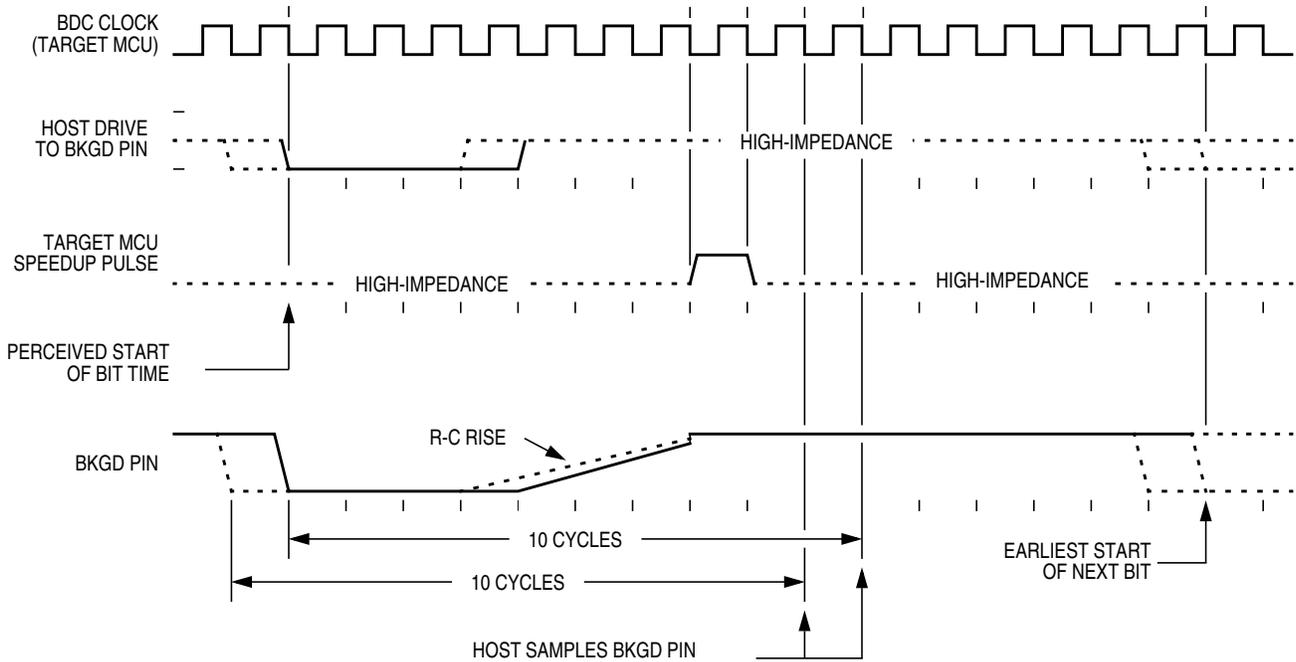
In master transmit mode, the first byte of data written to IIC1D following assertion of MST is used for the address transfer and should comprise of the calling address (in bit 7–bit 1) concatenated with the required R/W bit (in position bit 0).

converter yields the lower code (and vice-versa). However, even very small amounts of system noise can cause the converter to be indeterminate (between two codes) for a range of input voltages around the transition voltage. This range is normally around  $1/2\text{LSB}$  and will increase with noise. This error may be reduced by repeatedly sampling the input and averaging the result. Additionally the techniques discussed in Section 14.7.2.3 will reduce this error.

Non-monotonicity is defined as when, except for code jitter, the converter converts to a lower code for a higher input voltage. Missing codes are those values which are never converted for any input value.

In 8-bit or 10-bit mode, the ADC is guaranteed to be monotonic and to have no missing codes.

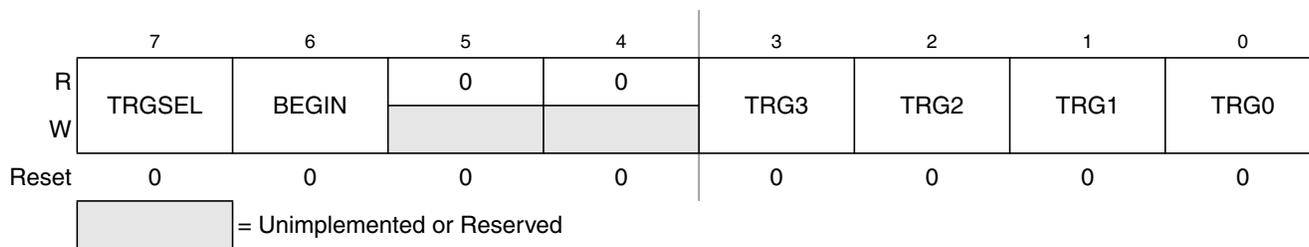
Figure 15-3 shows the host receiving a logic 1 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the perceived start of the bit time in the target MCU. The host holds the BKGD pin low long enough for the target to recognize it (at least two target BDC cycles). The host must release the low drive before the target MCU drives a brief active-high speedup pulse seven cycles after the perceived start of the bit time. The host should sample the bit level about 10 cycles after it started the bit time.



**Figure 15-3. BDC Target-to-Host Serial Bit Timing (Logic 1)**

### 15.4.3.8 Debug Trigger Register (DBGT)

This register can be read any time, but may be written only if ARM = 0, except bits 4 and 5 are hard-wired to 0s.



**Figure 15-8. Debug Trigger Register (DBGT)**

**Table 15-5. DBGT Register Field Descriptions**

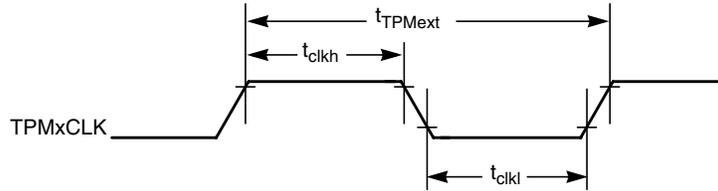
Field	Description
7 TRGSEL	<p><b>Trigger Type</b> — Controls whether the match outputs from comparators A and B are qualified with the opcode tracking logic in the debug module. If TRGSEL is set, a match signal from comparator A or B must propagate through the opcode tracking logic and a trigger event is only signalled to the FIFO logic if the opcode at the match address is actually executed.</p> <p>0 Trigger on access to compare address (force) 1 Trigger if opcode at compare address is executed (tag)</p>
6 BEGIN	<p><b>Begin/End Trigger Select</b> — Controls whether the FIFO starts filling at a trigger or fills in a circular manner until a trigger ends the capture of information. In event-only trigger modes, this bit is ignored and all debug runs are assumed to be begin traces.</p> <p>0 Data stored in FIFO until trigger (end trace) 1 Trigger initiates data storage (begin trace)</p>
3:0 TRG[3:0]	<p><b>Select Trigger Mode</b> — Selects one of nine triggering modes, as described below.</p> <p>0000 A-only 0001 A OR B 0010 A Then B 0011 Event-only B (store data) 0100 A then event-only B (store data) 0101 A AND B data (full mode) 0110 A AND NOT B data (full mode) 0111 Inside range: <math>A \leq \text{address} \leq B</math> 1000 Outside range: <math>\text{address} &lt; A</math> or <math>\text{address} &gt; B</math> 1001 – 1111 (No trigger)</p>

### A.10.2 Timer/PWM (TPM) Module Timing

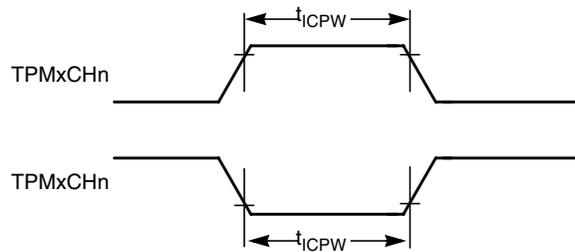
Synchronizer circuits determine the shortest input pulses that can be recognized or the fastest clock that can be used as the optional external source to the timer counter. These synchronizers operate from the current bus rate clock.

**Table A-14. TPM Input Timing**

Function	Symbol	Min	Max	Unit
External clock frequency	$f_{TPMext}$	dc	$f_{Bus}/4$	Hz
External clock period	$t_{TPMext}$	4	—	$t_{cyc}$
External clock high time	$t_{clkh}$	1.5	—	$t_{cyc}$
External clock low time	$t_{clkl}$	1.5	—	$t_{cyc}$
Input capture pulse width	$t_{ICPW}$	1.5	—	$t_{cyc}$



**Figure A-14. Timer External Clock**



**Figure A-15. Timer Input Capture Pulse**

## A.12 FLASH Specifications

This section provides details about program/erase times and program-erase endurance for the FLASH memory.

Program and erase operations do not require any special power sources other than the normal  $V_{DD}$  supply. For more detailed information about program/erase operations, see Chapter 4, “Memory.”

**Table A-16. FLASH Characteristics**

Num	C	Characteristic	Symbol	Min	Typ <sup>1</sup>	Max	Unit
1	P	Supply voltage for program/erase	$V_{\text{prog/erase}}$	2.7		5.5	V
2	P	Supply voltage for read operation	$V_{\text{Read}}$	2.7		5.5	V
3	P	Internal FCLK frequency <sup>2</sup>	$f_{\text{FCLK}}$	150		200	kHz
4	P	Internal FCLK period (1/FCLK)	$t_{\text{Fcy}}^3$	5		6.67	$\mu\text{s}$
5	P	Byte program time (random location) <sup>3</sup>	$t_{\text{prog}}$	9			$t_{\text{Fcy}}^3$
6	C	Byte program time (burst mode) <sup>3</sup>	$t_{\text{Burst}}$	4			$t_{\text{Fcy}}^3$
7	P	Page erase time <sup>3</sup>	$t_{\text{Page}}$	4000			$t_{\text{Fcy}}^3$
8	P	Mass erase time <sup>3</sup>	$t_{\text{Mass}}$	20,000			$t_{\text{Fcy}}^3$
9	C	Program/erase endurance <sup>4</sup> $T_L$ to $T_H = -40^\circ\text{C}$ to $+125^\circ\text{C}$ $T = 25^\circ\text{C}$		10,000 —	— 100,000	— —	cycles
10	C	Data retention <sup>5</sup>	$t_{\text{D\_ret}}$	15	100	—	years

<sup>1</sup> Typical values are based on characterization data at  $V_{DD} = 5.0\text{ V}$ ,  $25^\circ\text{C}$  unless otherwise stated.

<sup>2</sup> The frequency of this clock is controlled by a software setting.

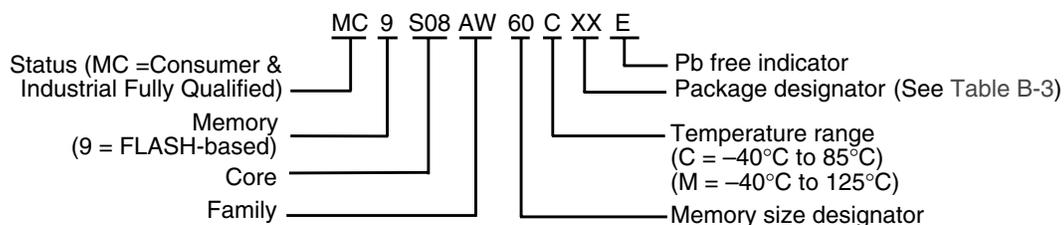
<sup>3</sup> These values are hardware state machine controlled. User code does not need to count cycles. This information supplied for calculating approximate time to program and erase.

<sup>4</sup> **Typical endurance for FLASH** was evaluated for this product family on the 9S12Dx64. For additional information on how Freescale Semiconductor defines typical endurance, please refer to Engineering Bulletin EB619/D, *Typical Endurance for Nonvolatile Memory*.

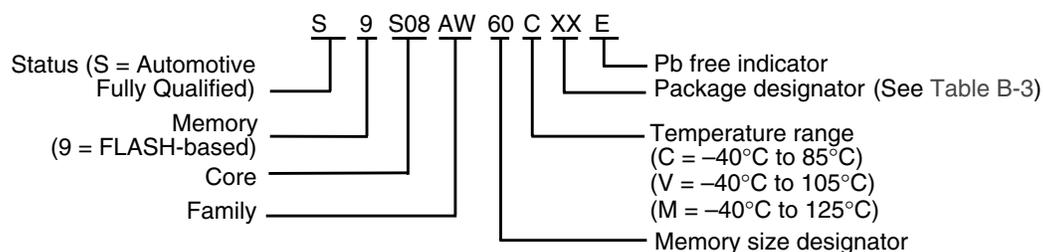
<sup>5</sup> **Typical data retention** values are based on intrinsic capability of the technology measured at high temperature and de-rated to  $25^\circ\text{C}$  using the Arrhenius equation. For additional information on how Freescale Semiconductor defines typical data retention, please refer to Engineering Bulletin EB618/D, *Typical Data Retention for Nonvolatile Memory*.

## B.2 Orderable Part Numbering System

### B.2.1 Consumer and Industrial Orderable Part Numbering System



### B.2.2 Automotive Orderable Part Numbering System

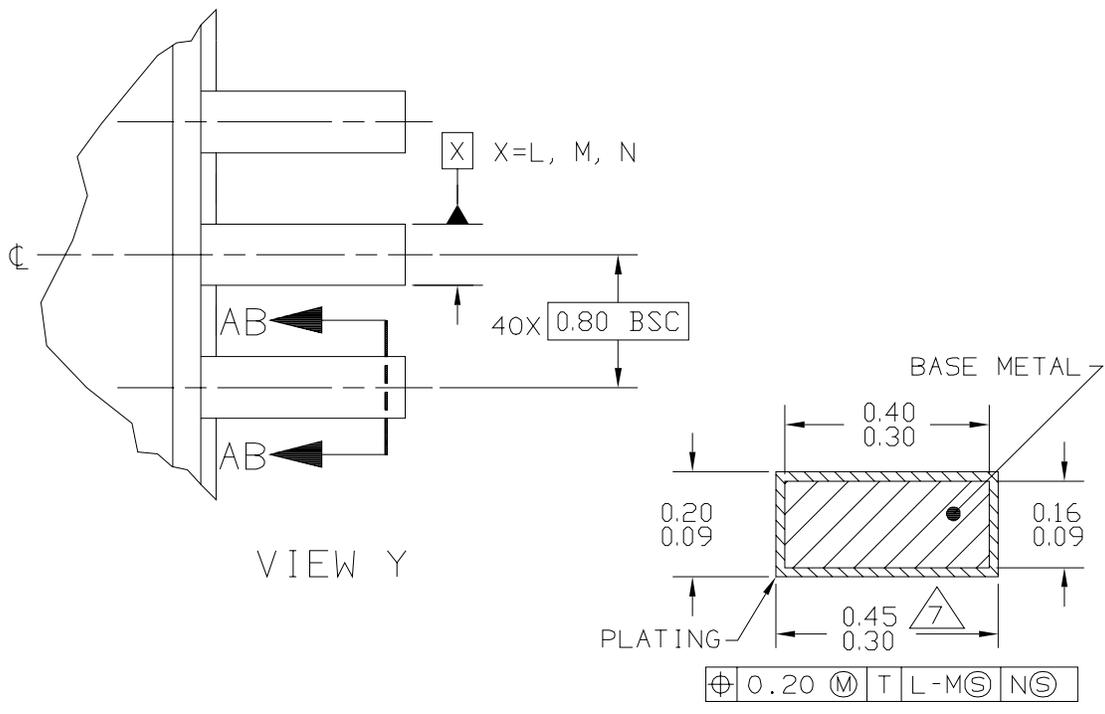


## B.3 Mechanical Drawings

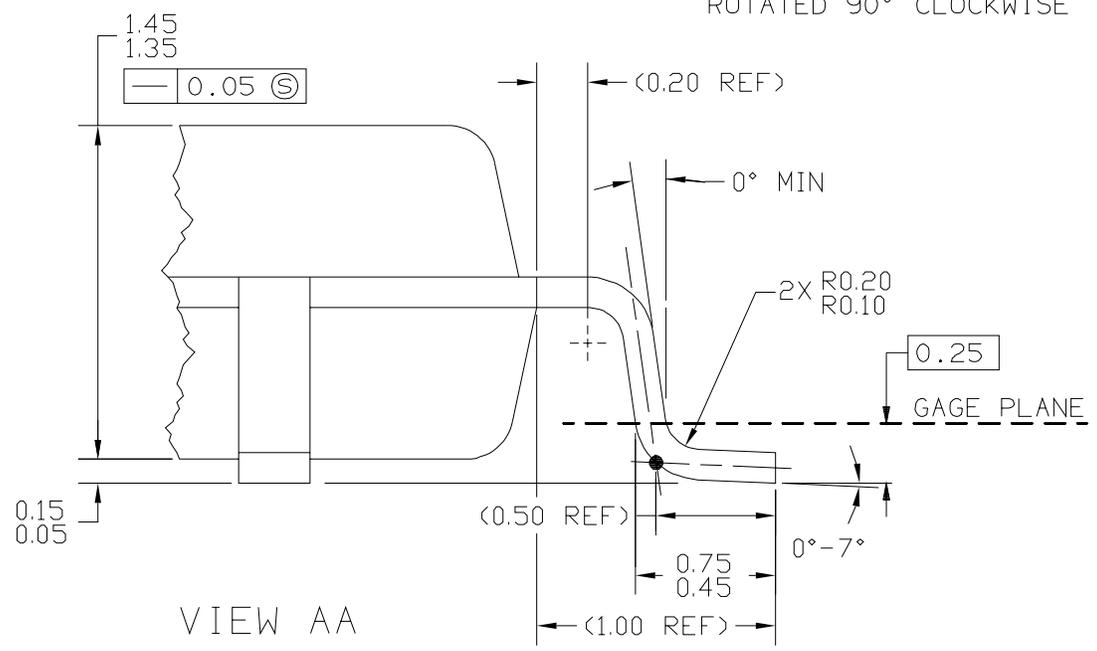
The following pages contain mechanical specifications for MC9S08AW60 Series package options. See Table B-3 for the document numbers that correspond to each package type.

**Table B-3. Package Information**

Pin Count	Type	Designator	Document No.
44	LQFP	FG	98ASS23225W
48	QFN	FD	98ARH99048A
64	LQFP	PU	98ASS23234W
64	QFP	FU	98ASB42844B



SECTION AB-AB  
ROTATED 90° CLOCKWISE



VIEW AA

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TITLE: 44 LD LQFP, 10 X 10 PKG, 0.8 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23225W	REV: D	
	CASE NUMBER: 824D-02	26 FEB 2007	
	STANDARD: JEDEC MS-026 BCB		